


SEP 12 2005

S/N 10/826,091

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: KAWAGUCHI ET AL. Examiner: LAVILLA
Serial No.: 10/826,091 Group Art Unit: 1775
Filed: APRIL 16, 2004 Docket No.: 10873.1436US01
Title: BONDING LAYER FORMING SOLUTION, METHOD OF PRODUCING
COPPER-TO-RESIN BONDING LAYER USING THE SOLUTION, AND
LAYERED PRODUCT OBTAINED THEREBY

CERTIFICATE UNDER 37 CFR 1.6(d): I hereby certify that this paper is being transmitted by facsimile to the
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By: 
Name: Gina M. Dahl

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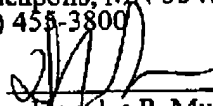
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Respectfully submitted,

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